SOT23-6L Plastic-Encapsulate ESD Protection Diodes

Features

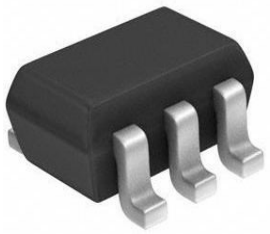
- Low leakage current
- SOT-23-6L surface mount package
- IEC 61000-4-2 (ESD Air): ±15kV
- IEC 61000-4-2 (ESD Contact): ±15kV
- IEC 61000-4-5 (Lightning 8/20μs): 4A

Reverse Working Voltage
5.0V Max.
Ultra small capacitance
$C_{I/O-GND}$=1.0pF(Typ.)
$C_{I/O-I/O}$=0.5pF(Typ.)

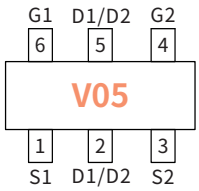
Applications

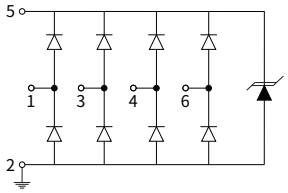
- Automotive Applications
- CAN Bus
- Electronic Control Units
- Body Control Units
- ADAS Control Units
- Power Train Control Units

SOT-23-6L



Function Diagram



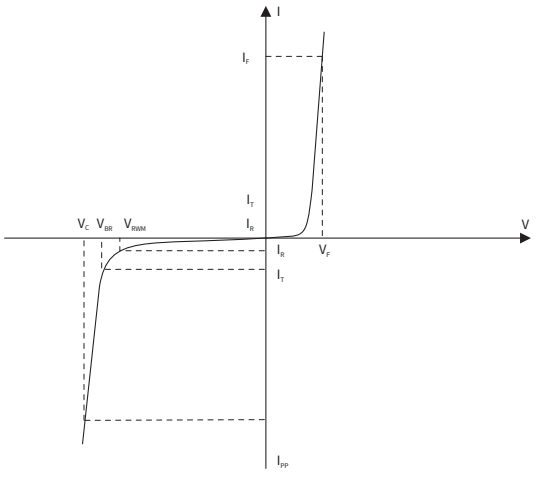


Maximum Ratings (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V_{ESD}	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2(Air)	±15	KV
		ESD per IEC 61000-4-2(Contact)	±15	KV
P_{PP}	Peak Pulse Power	tp = 8/20 μs	80	W
I_{PP}	Rated Peak Pulse Current	tp = 8/20 μs	4.0	A
T_J	Operating JunctionTemperature Range	—	-55 to +125	°C
T_{STG}	Operating JunctionTemperature Range	—	-55 to +150	°C

Electrical Parameter

SYMBOL	PARAMETER
V_C	Clamping Voltage @ I_{PP}
V_{BR}	Breakdown Voltage @ I_T
I_{PP}	Peak Pulse Current
I_T	Test Current
I_R	Reverse Leakage Current @ VRWM
V_{RWM}	Peak Reverse Working Voltage
P_{PP}	Peak Pulse Power Dissipation
C_J	Junction Capacitance @ V_R=0V,f=1MHz
I_F	Forward Current
V_F	Forward Voltage @I_F



Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	Min	Typ	Max	UNIT
Peak Reverse Working Voltage	V_{RWM}	T_a=25°C	—	—	5.0	V
Breakdown Voltage	V_{BR}	I_R=1mA,T_a=25°C	6.0	—	—	V
Reverse Leakage Current	I_R	V_{RWM}=5.0V,T_a=25°C	—	—	5.0	μA
Forward voltage	V_F	I_F=10mA,T_a=25°C	—	0.8	1.0	V
Clamping Voltage	V_C	I_{PP}=4.0A, t_p=8/20μs	—	12	15	V
Junction Capacitance	C_J	V_{RMW}=0V,f=1MHz,Between I/O pins	—	0.5	—	pF
		V_{RMW}=0V,f=1MHz,pin to GND	—	1.0	—	

Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)

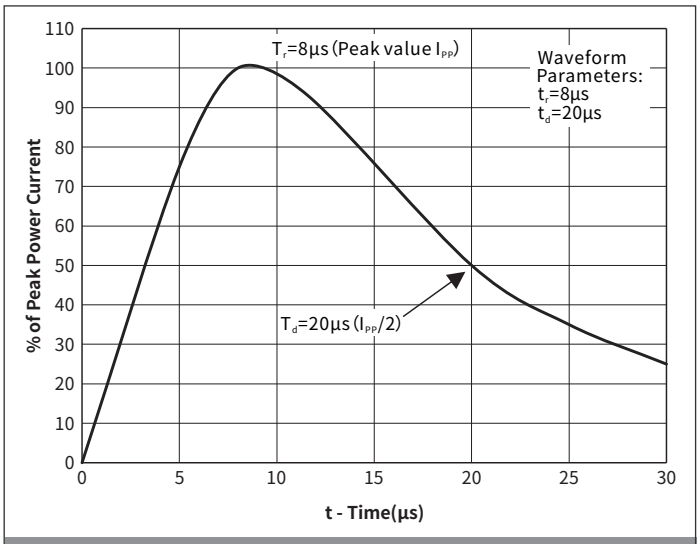


Fig.1 Pulse Waveform

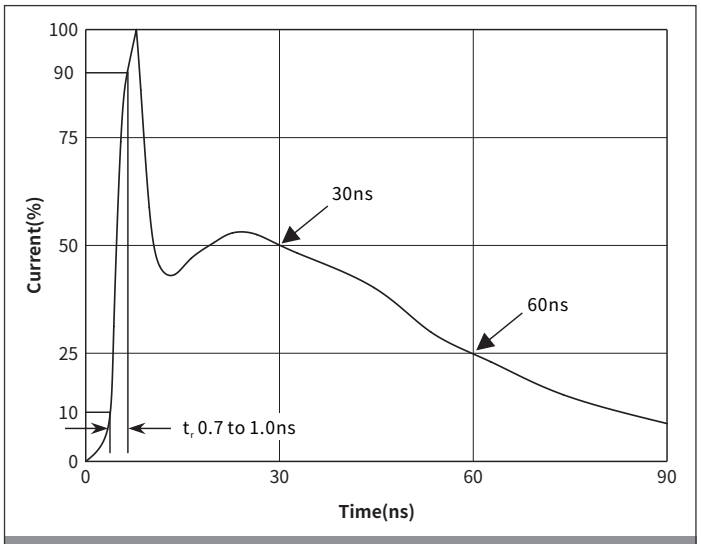


Fig.2 Pulse Waveform-ESD(IEC61000-4-2)

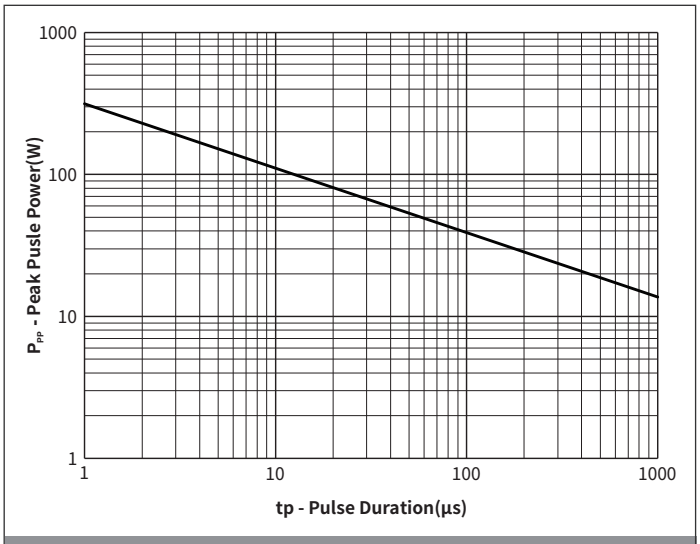


Fig.3 Peak Pulse Power vs. Pulse Time

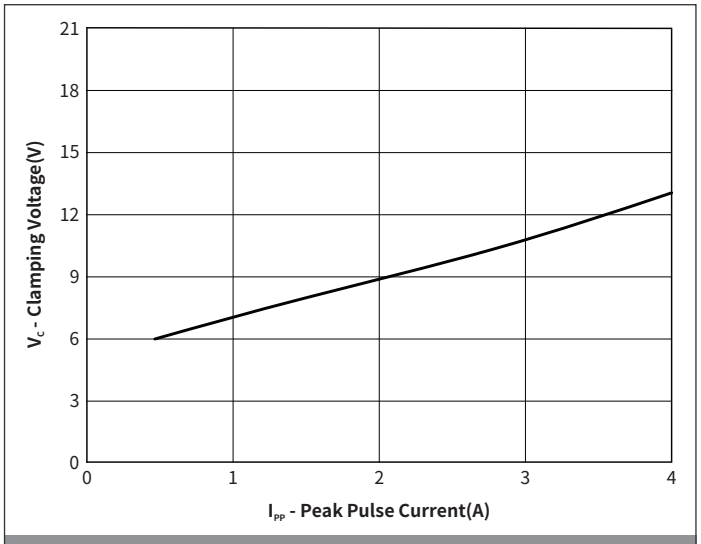
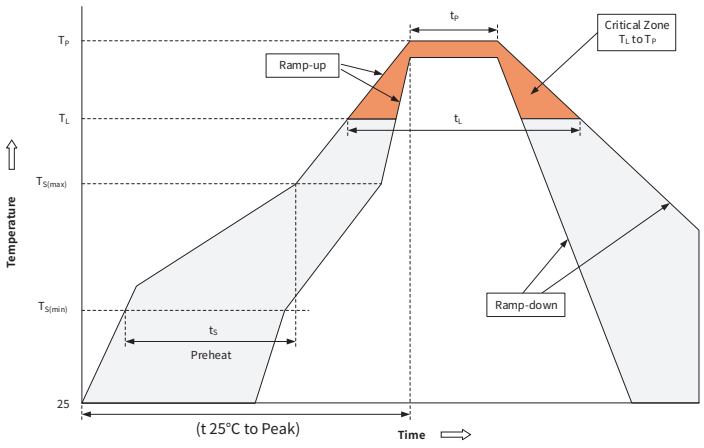


Fig.4 Clamping Voltage vs. Peak Pulse Current

Ordering Information

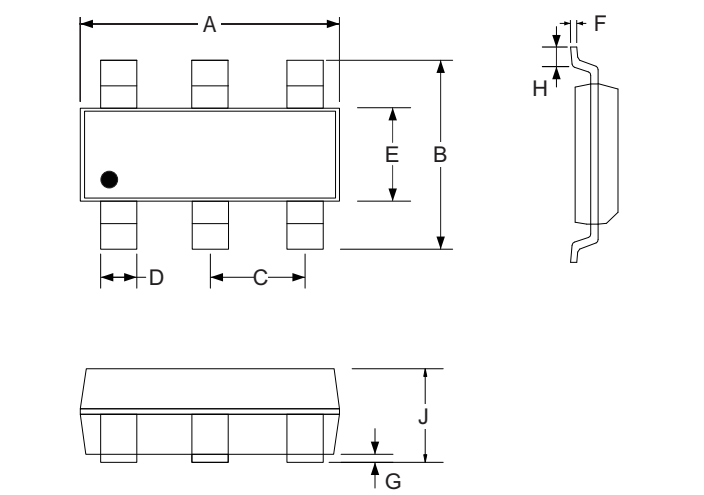
PREFERED P/N	PACKAGE	SIZE(mm)	DELIVERY MODE	MPQ(PCS)
SRV05-4A	SOT-23-6L	2.90×2.80×1.10	7'' REEL	3000

Recommended Soldering Conditions



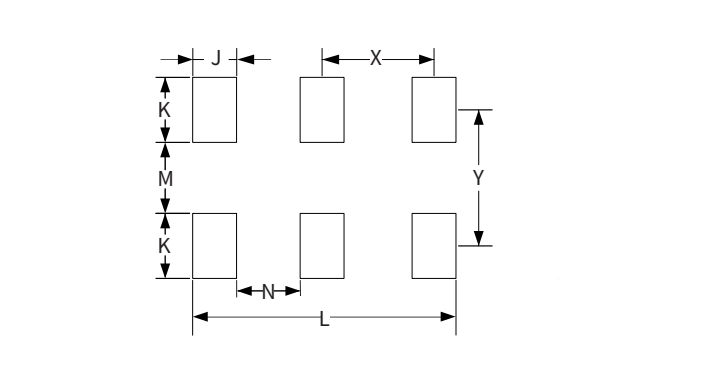
Profile Feature		Pb-Free Assembly
Pre-heat	Temperature Min ($T_{S(min)}$)	+150°C
	Temperature Max($T_{S(max)}$)	+200°C
	Time (Min to Max) (t_S)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C /sec. Max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C /sec. Max
Reflow	Temperature(T_L)(Liquid us)	+217°C
	Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		20-40secs
Ramp-down Rate		6°C /sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C

Package Outline Dimensions (SOT23-6L)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.00	0.110	0.118
B	2.60	3.00	0.102	0.118
C	0.93	0.97	0.037	0.038
D	0.41		0.016	
E	1.50	1.70	0.059	0.067
F	0.11	0.19	0.004	0.007
G	-	0.10	-	0.004
H	0.40	-	0.016	-
J	1.00	1.20	0.035	0.057

Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	0.60	-	0.024	-
K	0.90	-	0.035	-
M	-	1.40	-	0.055
N	-	0.35	-	0.014
X	-	0.95	-	0.037
Y	-	2.30	-	0.090
L	-	2.50	-	0.098

Note :

This soldering footprint is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.